

3Amp General Purpose Rectifiers

Reverse Voltage 50 ~ 1000 V, Forward Current 3.0 A





S3A ~ S3M

DO-214AB (SMC) Surface Mount Plastic Package RoHS compliant

DO-214AB (SMC)

FEATURES:

- 1. Low reverse leakage
- 2. High forward surge capability
- 3, High reliability
- 4. High temperature soldering guaranteed: 260 °C/10seconds
- 5. Lead and body according with RoHS standard
- 6. This product is available in AEC-Q101 Qualified and PPAP Capable also.

Note: For AEC-Q101 qualified products, please use suffix -AQ in the part number while ordering.

ABSOLUTE MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(Ratings at 25 °C ambient temperature unless otherwise specified.)

DESCRIPTION		SYMBOL	S3A	S3B	S3D	S3G	S3J	S3K	S3M	UNITS
Maximum Recurrent Peak Reverse Voltage		V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage		V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage		V _{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current		I _(AV)	3.0				А			
Non-repetitive peak forward surge current 8.3 ms single half sine-wave		I _{FSM}	100				А			
Maximum Forward Voltage @ I _F =3.0A DC		V _F	1.1				V			
Maximum reverse current	T _i =25°C		5					μA		
	T _j =125℃	I _R	100							
Type junction capacitance ¹		CJ	35			pF				
Thermal Resistance Junction to Lead		R _{th (J-L)}	10 (Тур.)			°C/W				
Thermal Resistance Junction to Ambient ²		Rth (j-a)	50 (Typ.)			°C/W				
Operating Junction Temperature Range		Tj	-55 to +150				°C			
Storage Temperature Range		T _{stg}	-55 to +150			٥C				

Note 1: Measured at 1MHz and applied reverse voltage of 4.0V D.C.

2. Thermal resistance from junction to ambient, PCB mounted.





TYPICAL CHARACTERISTIC CURVES

Figure 1.TYPICAL FORWARD CHARACTERISTIC

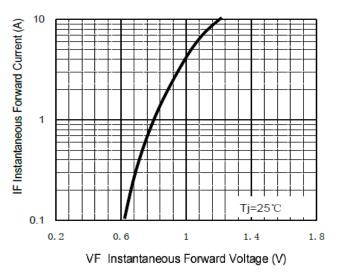


Figure 2.FORWARD CURRENT DERATING CURVE

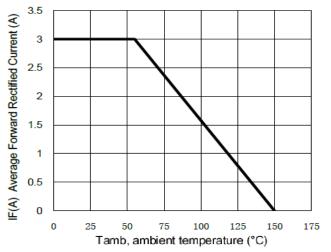
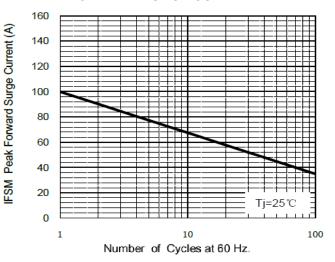


Figure 3. MAXIMUM NON REPETITIVE PEAK FORWARD SURGE CURRENT



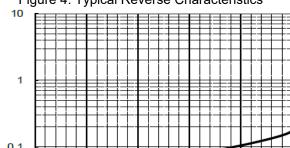
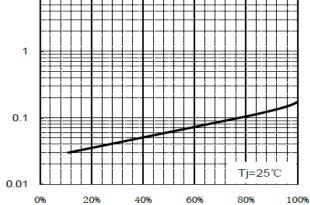


Figure 4. Typical Reverse Characteristics



Percent Of Rated Peak Reverse voltage %

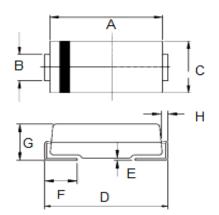
Reverse Current(uA)





PACKAGE DETAIL

DO-214AB (SMC)



Dim	Nim	Max
А	6.50	7.11
В	2.75	3.25
С	5.50	6.22
D	7.40	8.40
Е	0.051	0.203
F	0.76	1.40
G	2.00	2.70
Н	0.152	0.305

Dimensions in millimeters

Mechanical Data

Case:DO-214AB(SMC) Molded plastic **Epoxy:** UL 94V-0 rate flame retardant **Lead:** Pure tin plated, lead free





Recommended Reflow Solder Profiles

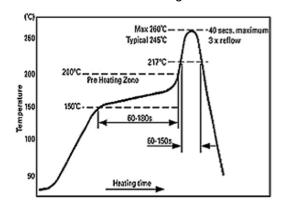
The recommended reflow solder profiles for Pb and Pb-free devices are shown below.

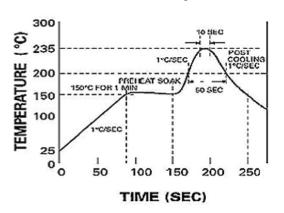
Figure 1 shows the recommended solder profile for devices that have Pb-free terminal plating, and where a Pb-free solder is used.

Figure 2 shows the recommended solder profile for devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with a leaded solder.

Figure 1

Figure 2





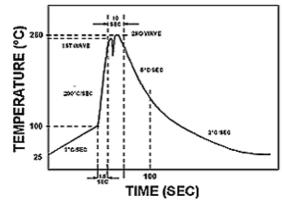
Profile Feature	Sn-Pb System	Pb-Free System		
Average Ramp-Up Rate	~3°C/second	~3°C/second		
Preheat – Temperature Range – Time	150-170°C 60-180 seconds	150-200°C 60-180 seconds		
Time maintained above: – Temperature – Time	200°C 30-50 seconds	217°C 60-150 seconds		
Peak Temperature	235°C	260°C max.		
Time within +0 -5°C of actual Peak	10 seconds	40 seconds		
Ramp-Down Rate	3°C/second max.	6°C/second max.		



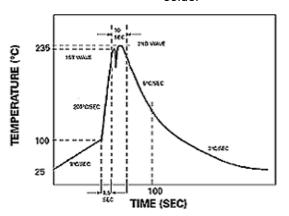


Recommended Wave Solder Profiles

The Recommended solder Profile For Devices with Pb-free terminal plating where a Pb-free solder is used



The Recommended solder Profile For Devices with Pbfree terminal plating used with leaded solder, or for devices with leaded terminal plating used with leaded solder



Wave Profiles in Tabular Form

Profile Feature	Sn-Pb System	Pb-free System
Average Ramp-Up Rate	~200°C/second	~200°C/second
Heating rate during preheat	Typical 1-2, Max 4°C/sec	Typical 1-2, Max 4°C/Sec
Final preheat Temperature	Within 125°C of Solder Temp	Within 125°C of Solder Temp
Peak Temperature	235°C	260°C max.
Time within +0 -5°C of actual Peak	10 seconds	10 seconds
Ramp-Down Rate	5°C/second max.	5°C/second max.





Recommended Product Storage Environment for Discrete Semiconductor Devices

This storage environment assumes that the Diodes and transistors are packed properly inside the original packing supplied by CDIL.

- · Temperature 5 °C to 30 °C
- · Humidity between 40 to 70 %RH
- · Air should be clean.
- · Avoid harmful gas or dust.
- $\cdot\,$ Avoid outdoor exposure or storage in areas subject to rain or water spraying .
- Avoid storage in areas subject to corrosive gas or dust. Product shall not be stored in areas exposed to direct sunlight.
- · Avoid rapid change of temperature.
- · Avoid condensation.
- · Mechanical stress such as vibration and impact shall be avoided.
- · The product shall not be placed directly on the floor.
- The product shall be stored on a plane area. They should not be turned upside down. They should not be placed against the wall.

Shelf Life of CDIL Products

The shelf life of products is the period from product manufacture to shipment to customers. The product can be unconditionally shipped within this period. The period is defined as 2 years.

If products are stored longer than the shelf life of 2 years the products shall be subjected to quality check as per CDIL quality procedure.

The products are further warranted for another one year after the date of shipment subject to the above conditions in CDIL original packing.

Floor Life of CDIL Products and MSL Level

When the products are opened from the original packing, the floor life will start. For this, the following JEDEC table may be referred:

JEDEC MSL Level				
Level	Time	Condition		
1	Unlimited	≤30 °C / 85% RH		
2	1 Year	≤30 °C / 60% RH		
2a	4 Weeks	≤30 °C / 60% RH		
3	168 Hours	≤30 °C / 60% RH		
4	72 Hours	≤30 °C / 60% RH		
5	48 Hours	≤30 °C / 60% RH		
5a	24 Hours	≤30 °C / 60% RH		
6	Time on Label(TOL)	≤30 °C / 60% RH		





Customer Notes

Component Disposal Instructions

- 1. CDIL Semiconductor Devices are RoHS compliant, customers are requested to please dispose as per prevailing Environmental Legislation of their Country.
- 2. In Europe, please dispose as per EU Directive 2002/96/EC on Waste Electrical and Electronic Equipment (WEEE).

Disclaimer

The product information and the selection guides facilitate selection of the CDIL's Semiconductor Device(s) best suited for application in your product(s) as per your requirement. It is recommended that you completely review our Data Sheet(s) so as to confirm that the Device(s) meet functionality parameters for your application. The information furnished in the Data Sheet and on the CDIL Web Site/CD are believed to be accurate and reliable. CDIL however, does not assume responsibility for inaccuracies or incomplete information. Furthermore, CDIL does not assume liability whatsoever, arising out of the application or use of any CDIL product; neither does it convey any license under its patent rights nor rights of others. These products are not designed for use in life saving/support appliances or systems. CDIL customers selling these products (either as individual Semiconductor Devices or incorporated in their end products), in any life saving/support appliances or systems or applications do so at their own risk and CDIL will not be responsible for any damages resulting from such sale(s).

CDIL strives for continuous improvement and reserves the right to change the specifications of its products without prior notice.



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